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3M™ EMI/EMC Electronic Materials



Solutions for Today's Electronics

- EMI Shielding Tapes
- EMI Grounding Adhesives and Gaskets
- EMI Absorbers
- Flux Field Directional Materials
- NFC, Wireless Power, Magnetic Shielding Materials



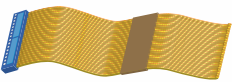
Easy-to-use shielding, absorbing, grounding and bonding technology for today's electronics

The continuing trend toward designing electronic devices with smaller enclosures, denser circuits and higher speeds has made managing electromagnetic/radio frequency interference (EMI/RFI) and electrostatic discharge (ESD) a growing challenge for electronics manufacturers.

3M can help you meet that challenge, with a variety of advanced shielding and grounding solutions designed to help you speed assembly time... reduce weight... save space... control costs... and give you more design flexibility. Let 3M help you get connected!

Laptop EMI/EMC Solutions

3M Multi-functional EMI Shielding, Grounding and Heat Spreading Solutions for LED and other heat sources device temperature management



3M™ EMI Absorbers AB5050/AB6005/AB7050 to reduce EMI Noise level within device or on Flex/Connector

3M™ Electrically Conductive Adhesive Transfer Tape 9707/9709S/9720S/9750 for Flex/PCB grounding and attachment, grounded parts assembly versus screws and clips. Lower device bias, reduce flex EMI interference.

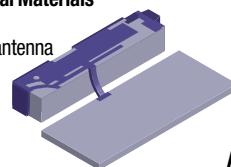


3M EMI Absorbers AB5050/AB6005/AB7050 to reduce the EMI noise radiation from high speed devices like CPU/MPU/memory. Attach AB series sheet on the specific noise source.

3M™ Electrically Conductive Gasket ECG-7073 for grounding and EMI shielding.

3M EMI Absorbers AB7050/AB5100 to reduce EMI noise within enclosure / EMI Faraday Cage / Reduce cavity resonance. Attach absorber sheet on the wall of shielding parts.

3M™ Flux Field Directional Materials EM16TF/RFIC15 for improved NFC & RFID antenna read range performance. Less eddy current losses in surrounding materials.

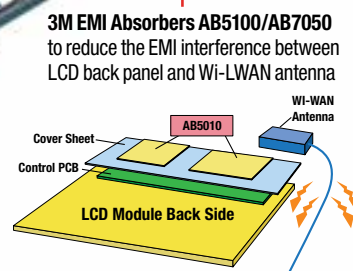


Read Antenna

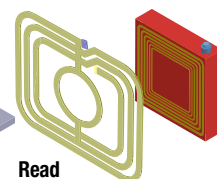
Very soft and conformable 3M™ Electrically Conductive Foam Gasket Materials MSG-6100 for grounding, gap filling and EMI shielding

3M™ EMI Shielding Foil and Fabric Tape for display grounding and EMI Shielding

- LCD Driver EMI Shielding
- 3M EMI Shielding Foil Tapes 1170 and 1183
- 3M EMI Shielding Fabric Tapes CN3490, CN3190 and CEF-3T



End user device using NFC/RFID Antenna & 3M Flux Field Directional Material (FFDM)

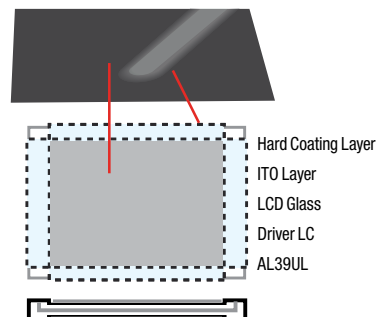


3M EMI/EMC Solutions

Foil and Fabric Tapes

| Product | Backing | Adhesive | Total Thickness mils (mm) | Features |
|---|--|---|-------------------------------------|--|
| 3M™ Metallized Cloth | | | | |
| 2191FR | Nickel on copper-plated polyester ripstop fabric | Acrylic Conductive | 5.5 (0.140) | Lightweight, conformable, oxidation resistant and high strength for EMI shielding and grounding. Easily die cut. |
| AG-0927 | Silver-coated polyester fabric | Acrylic Conductive | 4.3 (0.110) | Lightweight, conformable, oxidation resistant and high strength for EMI shielding and grounding. Easily die cut. |
| AU-2190 | Gold-coated polyester fabric | Acrylic Conductive | 4.3 (0.110) | Lightweight, conformable, oxidation resistant and high strength for EMI shielding and grounding. Easily die cut. |
| X-7001 | Copper-plated polyester ripstop fabric | Acrylic Conductive Coated on Both Sides | 4.3 (0.110) | Typically used to bond two surfaces, both physically and electrically. Also can provide EMI shielding, static charge draining, grounding. Lightweight, conformable and easily die cut. |
| CN 3190 | Nickel on copper-plated polyester ripstop fabric | Acrylic Conductive | 4.3 (0.110) | Lightweight, conformable, oxidation resistant and high strength for EMI shielding and grounding. |
| CN3490 | Non-woven copper-nickel fabric | Acrylic Conductive | 2.4 (.06) | Lightweight, thin, conformable non-woven fabric. Ideal for shielding, grounding, and static dissipation. Easily die cut. |
| CN4490 | Non-woven copper-nickel fabric | Double Coated Acrylic Conductive | 2.0 (.05) | Double coated with adhesive. Lightweight, thin, conformable non-woven fabric. Ideal for shielding, grounding, and static dissipation. Ideal for use as a thin, conductive, repositionable gasket material. Easily die cut. |
| CEF-6** | Cu/Ni plated fabric | Acrylic Conductive coated on both sides | 5.5 (0.14) | Bonding and grounding two surfaces. EMI shielding, static discharge draining. Flexible and conformable design. |
| CEF-6R ** | Cu/Ni plated fabric | Acrylic Conductive coated on both sides | 4.7 (0.12) | Bonding and grounding two surfaces. EMI shielding, static discharge draining. Flexible and conformable design. |
| CEF-1** | Cu/Ni plated fabric | Acrylic Conductive | 4.3 (0.11) | Bonding and grounding two surfaces. EMI shielding, static discharge draining. Flexible and conformable design. |
| CEF-3** | Cu/Ni plated fabric | Acrylic Conductive | 4.7 (0.12) | Bonding and grounding two surfaces. EMI shielding, static discharge draining. Flexible and conformable design. |
| CEF-8** | Cu/Ni plated fabric | Acrylic Conductive coated on both sides | 3.0 (0.075) | Bonding and grounding two surfaces. EMI shielding, static discharge draining. Flexible and conformable design. |
| CEF-3T** CEF-3B** | Cu/Ni plated fabric | Acrylic Conductive | 2.4 (0.06) Grey 2.4 (0.06) Black | Bonding and grounding two surfaces. EMI shielding, static discharge draining. Flexible and conformable design. |
| 3M™ EMI Shielding Sheets and Films | | | | |
| CU-10S** | Epoxy FR film + copper foil | None | 6.7 (0.170) | Softened copper foil with flame-retardant film on one side. Excellent EMI shielding for PCBs and assemblies. Lightweight, flexible and easily die cut. |

**Products are special order in the USA. Please contact your 3M sales support for details.



EMI Custom Foil Tape Solutions

- Shielding
- Grounding
- ESD Protection
- Conformability
- Ease of use in assembly
- Customized thickness

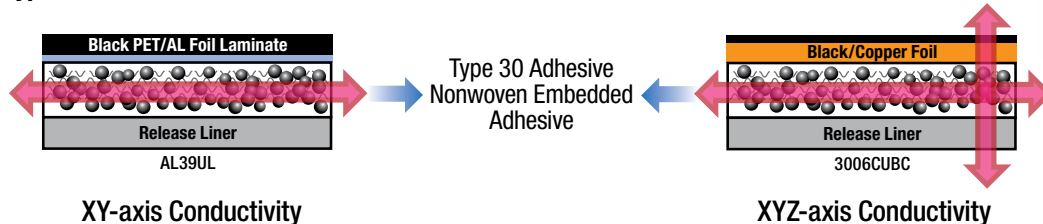
* For 3M custom solutions please contact your local 3M product specialist. Products are special order. AL39UL and 3006ALB.

3M offers a wide range of EMI/RFI shielding tapes and absorbing materials, mesh and sleeving products, gaskets and conductive materials.



Customized XY and XYZ Foil & Fabric Tape Options

Typical Product Constructions



3M EMI/EMC Solutions

Foil and Fabric Tapes

These solutions include an innovative line of 3M™ Electromagnetic Compatible Products that can control electromagnetic interference from internal sources, limit EMI susceptibility from external sources and help manufacturers meet high certification standards around the world.

- Provide electromagnetic compatibility
- Shield or absorb electromagnetic and radio frequency interference
- Ground sensitive electronic components and boards
- Cushion components
- Protect cables
- Provide conductive properties

3M™ EMC Products can provide EMI/RFI shielding and absorbing, static charge grounding, anti-static masking, cushioning, mechanical protection and conductive properties for a wide variety of applications.

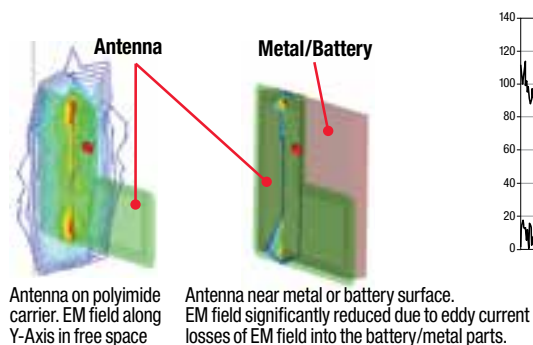


| Product | Backing | Adhesive | Total Thickness mils (mm) | Features |
|--|--|---|---------------------------|---|
| 3M™ Aluminum Foil | | | | |
| 300PL | 1.9 mil aluminum foil* | Acrylic Non-Conductive | 3.0 (0.078) | Economical EMI shielding aluminum foil tape. Excellent adhesion and environmental resistance. |
| 1120 | 2 mil aluminum foil | Acrylic Conductive | 4.0 (0.102) | For EMI shielding, static charge draining, grounding. Good for cable wrap. Easily die cut. |
| 1170 | 2 mil aluminum foil | Acrylic Conductive | 3.2 (0.081) | For EMI shielding, static charge draining, grounding. Easily die cut. |
| 1178** | 1.8 mil aluminum foil | Acrylic Conductive | 3.3 (0.084) | EMI shielding, static discharge draining and grounding. |
| AL-25BT** | 1 mil aluminum foil | Acrylic Conductive | 2.4 (0.061) | For EMI shielding, static charge draining, grounding. Easily die cut. |
| AL-25DC** | 1 mil aluminum foil | Acrylic Conductive Coated on Both Sides | 3.3 (0.084) | For EMI shielding, static charge draining, grounding. Easily die cut. |
| AL-50BT** | 2 mil aluminum foil | Acrylic Conductive | 3.1 (0.079) | For EMI shielding, static charge draining, grounding. Easily die cut. |
| 1115B | 4.5 mil aluminum foil | Acrylic Conductive | 6.0 (0.152) | For EMI shielding, grounding and static dissipation. 4.5 mil thickness provides excellent shielding and structural support characteristics. Easily die cut. |
| 3M™ Aluminum Foil Laminated with Polyester Film | | | | |
| AL-36FR | 1 mil aluminum foil + polyester film | Acrylic Conductive | 2.4 (0.061) | Foil backing laminated with polyester film. Good resistance to oxidation, solvents and oils. Easily die cut. |
| AL-36NC | 1 mil aluminum foil + polyester film | Acrylic Non-Conductive | 2.2 (0.055) | Foil backing laminated with polyester film. Good resistance to oxidation, solvents and oils. Easily die cut. |
| AL-37BLK** | 1 mil aluminum foil + black matte polyester film | Acrylic Conductive | 2.8 (0.071) | Foil backing laminated with polyester film. Matte surface finish. Good electrical insulation, resistance to oxidation, solvents and oils. Easily die cut. |
| CEAP-1** | 2.0 Aluminum Foil + PET film | Acrylic Non-Conductive | 3.2 (0.080) | EMI shielding, assembly aide tape. |
| CEAP-6B** | 1.0-1.4 total Aluminum Foil + Black PET film | Acrylic Conductive | 2.6 (0.065) | EMI shielding, static discharge draining, grounding. |
| 3M™ Copper Foil | | | | |
| 508SN | 1.4 mil copper foil | Acrylic Non-Conductive | 3.2 (0.080) | Economical EMI shielding on a wide range of applications. |
| 1125 | 1.4 mil copper foil | Acrylic Non-Conductive | 3.5 (0.089) | For EMI shielding on a wide range of applications. Easily die cut. |
| 1126 | 1.4 mil copper foil | Acrylic Conductive | 3.5 (0.089) | For EMI shielding, static charge draining when grounded. Easily die cut. |
| 1181 | 1.4 mil copper foil | Acrylic Conductive | 2.6 (0.066) | For EMI shielding, static charge draining, grounding. Easily die cut. |
| 1182 | 1.4 mil copper foil | Acrylic Conductive Coated on Both Sides | 3.5 (0.089) | Typically used to bond two surfaces, both physically and electrically. Also can provide EMI shielding, static charge draining, grounding. Easily die cut. |
| 1183 | 1.4 mil tin-plated copper foil | Acrylic Conductive | 2.6 (0.066) | Oxidation resistant for long-term EMI shielding, static charge draining, grounding. Solderable and easily die cut. |
| 1188** | 1.3 mil Copper Foil | Acrylic Conductive | 2.9 (0.074) | EMI shielding, static discharge draining and grounding. |
| 1194 | 1.4 mil copper foil | Acrylic Non-Conductive | 2.6 (0.066) | For EMI shielding, static charge draining, grounding. Easily die cut. |
| CU-35C** | 1.4 mil copper foil | Acrylic Conductive | 2.8 (0.07) | For grounding and EMI shielding. Solderable and easily die cut. |
| CEC-2** | 0.79 mil copper foil | Acrylic Conductive coated on both sides | 2.2 (0.055) | EMI shielding, static discharge draining and grounding. |
| CEC-2B** | 1.18 mil copper foil | Acrylic Conductive coated on both sides | 3.6 (0.092) | Differential adhesion for side 1 vs side 2 for easier rework. EMI shielding, static discharge draining, assembly of substrates and grounding. |
| CEC-3** | 0.79 mil copper foil | Acrylic Conductive | 2.0 (0.05) | EMI shielding, static discharge draining and grounding. |
| 3M™ Embossed Foil | | | | |
| 1245 | Embossed copper foil | Acrylic Non-Conductive | 4.0 (0.102) | For EMI shielding, static charge draining, grounding. Solderable and easily die cut. |
| 1267 | Embossed aluminum foil | Acrylic Non-Conductive | 5.0 (0.127) | For EMI shielding, static charge draining, grounding. Solderable and easily die cut. |
| 1345 | Embossed tin-plated copper foil | Acrylic Non-Conductive | 4.0 (0.102) | Oxidation resistant for long-term EMI shielding, static charge draining, grounding. Solderable and easily die cut. |
| 2245** | Embossed copper foil | Acrylic Conductive | 4.0 (0.102) | For grounding and EMI shielding. Solderable and easily die cut. |
| 3245 | Reverse embossed copper foil | Acrylic Conductive | 5.9 (0.150) | For EMI shielding, static charge draining, grounding. Solderable, easily die cut. |

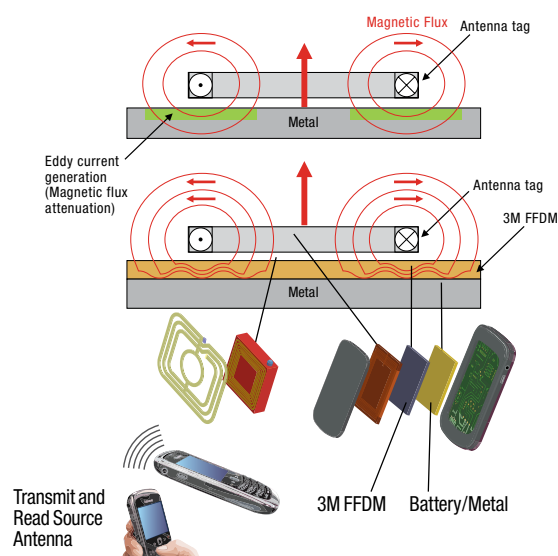
*For information on the copper foil version of 300PL, contact your 3M representative.

**Products are special order in the USA. Please contact your 3M sales support for details.

3M™ Flux Field Directional Materials for NFC/RFID and Wireless Power Applications

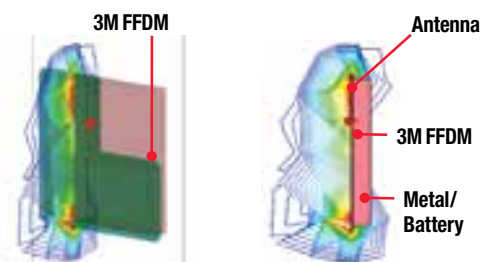
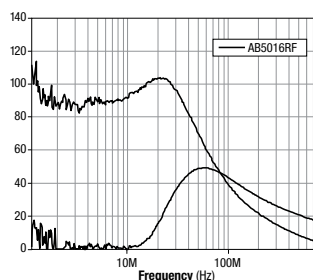


Improve NFC/RFID Antenna Read Range with 3M Flux Field Directional Materials (FFDM)



3M Flux Field Directional Materials EM16TF and RFIC15 reduce eddy current losses and improve read range

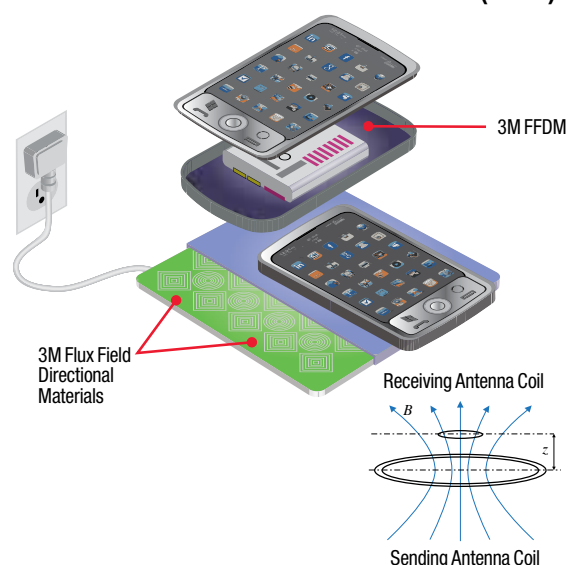
3M Solution: Thin / high permeability, low signal loss FFDM (Optimized to 13.56MHz)



Antenna with 3M FFDM between the antenna and metal/battery parts. EM field strength increased significantly with 3M FFDM use.

Side view of antenna with 3M FFDM between antenna and metal/battery surface.

Improve Power Transfer Efficiency and Range with 3M Flux Field Directional Materials (FFDM)

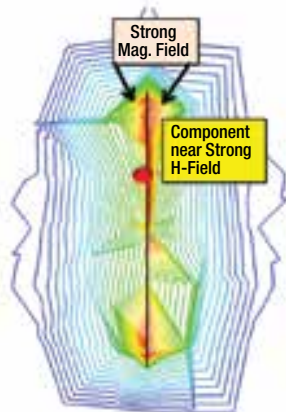


3M Flux Field Directional Materials EM80KM and RFIC30 improve EM energy transfer via inductive coupling (short range) or magnetic coupled resonance (longer range)

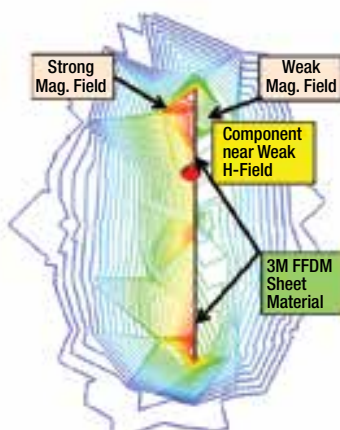
3M Solution: High permeability, low energy loss FFDM at operating frequencies

3M™ Flux Field Directional Materials (FFDM) for Magnetic Shielding Applications

H-Field of Device No Magnetic Shielding



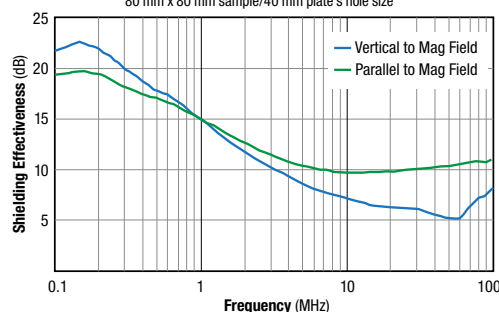
H-Field of Device FFDM Magnetic Shielding



3M FFDMs can be used to provide magnetic shielding of stray field generating devices or materials that impact neighbor device or component performance (i.e. inductor, wireless power, etc.).

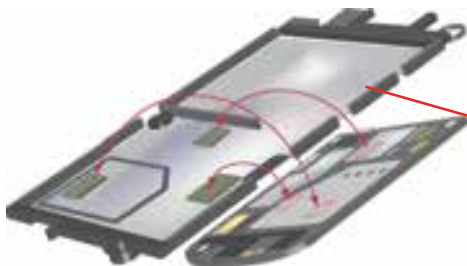
3M FFDM Type EM80KM

0.02 mm Soft Magnetic Layer Thickness
KEC Magnetic Field Test Method
80 mm x 80 mm sample/40 mm plate x hole size

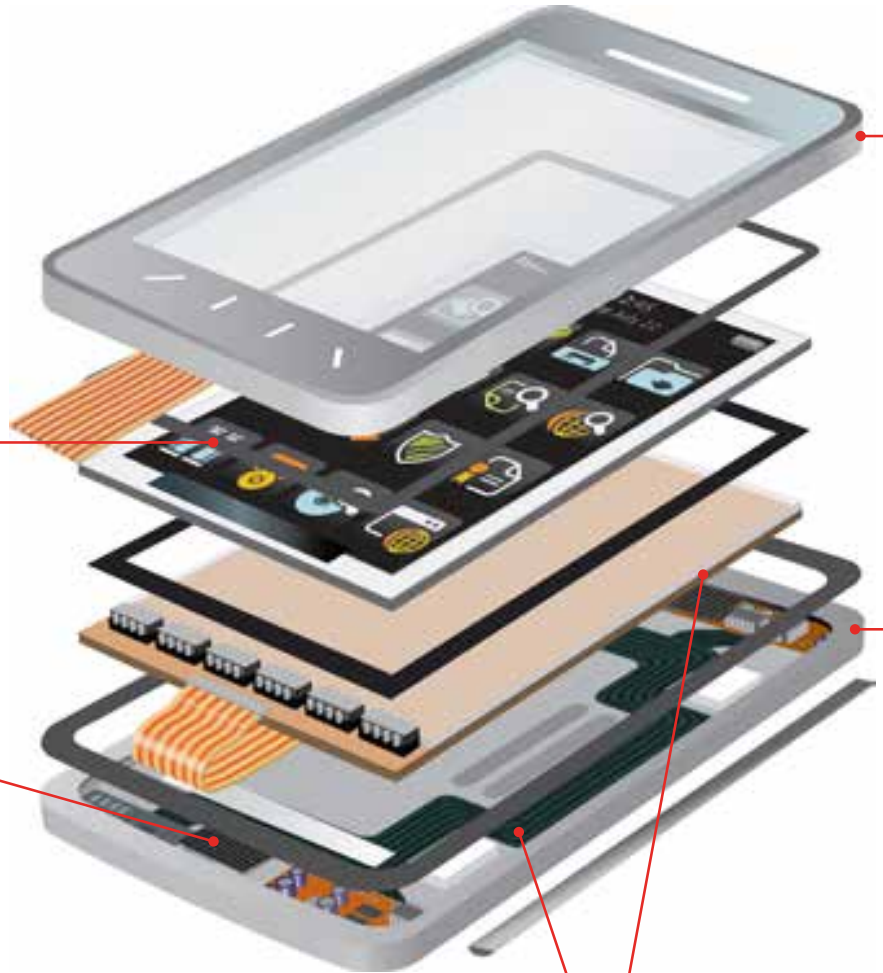


Mobile Handheld & Tablet EMI/EMC Solutions

3M Multi-functional EMI Shielding, Grounding and Heat Spreading Solutions.
Hot device heat spreading & grounding, LED heat spreading and attachment. EMI and thermal management materials.



3M™ Electrically Conductive Gaskets
ECG-7050/ECG-8055/MSG-6100



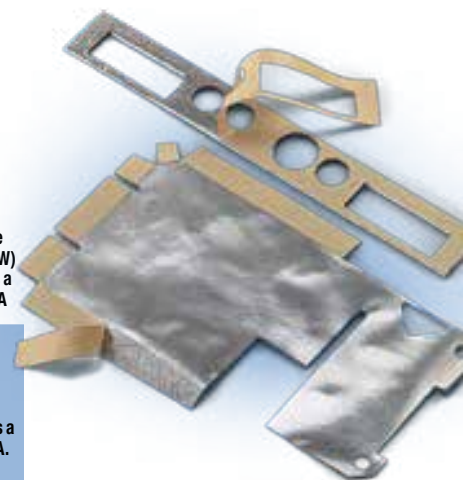
As frequency increases, is the “bond line gap” leading to stray EMI?
(Cross talk, spurious EMI, signal degradation and noise.)

| Problem | Solution |
|---|--|
| <p>Higher frequencies require optimized grounding and Faraday Cage design</p> <p>Poor “through tape” EMI Shielding leads to lower EMI SE at High Frequencies.</p> <p>At High Frequencies, the effect of “through the tape thickness” EMI gaps or EMI slits is to allow EMI leakage. If the effective EMI gap/slit does not = “0”, EMI energy at high frequency can pass through a “standard conductive adhesive tape material” via the gap related to the adhesive thickness. The “Tape Bond Line Gap/Slit leakage effect” leads to poor EMI Shielding, cross-talk, degraded Signal-to-Noise ratio, etc.</p> | <p>Inherent bond line thickness EMI Shielding using 3M™ Electrically Conductive Adhesive Transfer Tape (ECATT)</p> <p>Standard electrically conductive tape leads to EMI leakage through bond line tape thickness.</p> <p>3M ECATT 9709SL</p> <p>3M ECATT with inherent EMI shielding at the bond line provides significantly reduced crosstalk, stray EMI, noise in circuit, antennae effects, FPC susceptibility and spurious emissions.</p> <p>3M Electrically Conductive Adhesive Transfer Tape 9709SL used for FPC grounding and EMI Shielding</p> <p>Flex Printed Circuit</p> <ul style="list-style-type: none"> Flex 3M ECATT 9709SL Grounding Surface Substrate Layer <p>3M ECATT 9707, 9709S</p> |

These long-lasting adhesive transfer tapes can eliminate the need for screws and mechanical fasteners – while allowing the use of lighter, more compact fabric and layered foil shielding materials.

And, unlike other electrically conductive adhesives that can be messy and difficult to handle, 3M delivers advanced adhesive and conductive properties in an easy-to-use, pressure-sensitive tape that can be hand or machine applied and die cut to virtually any shape!

| | Contact Resistance (R ohms) between a Gold Flexible Test Strip and a SS panel using the 3M ECATT | Bond Line EMI Shielding (Bond Line Gap/Slit EMI Shielding Potential) | Potential to improve contact R of a Flex to a PCB grounding locations via improved surface conformability and XYZ conductive potential with an ECATT product type vs. a generic Z-axis only conductive PSA | Adhesion to SS type substrate/3M TM/24 hour RT dwell | Ease of Rework based on a standard set of substrates | Thermal Conductivity (W/mK) or an effective Thermal Resistance (C/W) for a given thickness vs a generic Z-Axis only PSA |
|---------|---|--|--|--|---|---|
| Product | Gold flex bonded to SS using the ECATT. "Best" results relate to a lower contact R potential on SS. Contact R can vary with SS type tested as the oxide layer thickness on a SS type affects the final R results. See note 1. | Best = High dB EMI Shielding in Bond Line "Gap/Slit" | Contact R between a Flex and a PCB | Peel Strength | ECATT design can effect rework based on acrylic adhesive type & conductive filler type. | Effective Thermal resistance and Thermal Conductivity vs a generic Z-Axis only PSA. |
| 9703 | Best | | Good | Good | Better | Good |
| 9704 | Best | | Good | Best | Good | Good |
| 9705 | Best | | Good | Good | Better | Good |
| 9706 | Best | | Good | Best | Good | Good |
| 9707 | Best | Best | Best | Best | Good | Best |
| 9709 | Good | Best | Best | Good | Better | Best |
| 9709S | Best | Best | Best | Good | Better | Best |
| 9709SL | Best | Best | Best | Good | Better | Best |
| 7805 | Good | Better | Good | Best | Better | Better |
| 7850 | Good | Good | Good | Best | Good | Best |
| 7772 | Better | Good | Good | Good | Good | Good |
| 9712 | Good | Good | Good | Better | Good | Good |
| 9713 | Better | Good | Good | Good | Good | Good |
| 9719 | Good | Good | Good | Better | Good | Good |
| 9720S | Better | Good | Good | Good | Good | Good |
| 9723 | Better | Good | Better | Best | Good | Good |
| 9750 | Best | Best | Best | Best | Good | Good |
| 9732 | Best | Better | Better | Best | Good | Good |
| 9760 | Best | Better | Better | Good | Best | Good |
| 9764 | Better | Better | Good | Good | Best | Good |
| 9780 | Better | Better | Good | Good | Best | Good |



3M™ Electrically Conductive Adhesive Transfer Tape (ECATT) Selection Process

Selection of Grounding, EMI Shielding and attachment ECATTs consists of determining several application requirements: For example, an ECATT general selection process could take into consideration items such as, but not limited to:

- 1 Determine contact R target
- 2 Define contact surface type
- 3 Adhesion level desired - from High-Medium-Standard Adhesion, and High/Low adhesion sided ECATTs
- 4 Bond line thickness
- 5 Z or XYZ conductive type ECATT
- 6 Operating temperature range and environmental conditions
- 7 EMI Shielding in bond line "Gap/Slit" for high frequencies
- 8 Determine contact area for ECATT used for R and adhesion of surfaces
- 9 Assembly Pressure, temperature and time limits
- 10 After assembly bond line stresses and need for added mechanical support
























3M EMI/EMC Solutions

3M™ Electrically Conductive Adhesive Transfer Tapes

3M™ Electrically Conductive Adhesive Transfer Tapes are designed to help you save time in a variety of specialized electronics assembly operations – from attaching EMI shields and gaskets to grounding and bonding flexible circuits and PCBs – while improving the performance and reliability of your finished products.

3M ECATT General Overview Comparative Reference Table

| Product | Pictorial Design | Thickness (µm) | Z or XYZ Conductivity (Based on 3M Test Method) | Conductive Filler Type | Adhesive Type | Features, Advantages, and Benefits | Contact Resistance (R ohms) between a Copper foil test panel and a 2nd Sheet of a Copper foil test panel using the 3M ECATT | Contact Resistance (R ohms) between a Gold Flexible Test Strip and a Gold Pad PCB panel using the 3M ECATT |
|---------|---|----------------|---|------------------------|---|---|--|--|
| | | | | | | | Copper foil bonded to a Copper Foil using the 3M ECATT / 3M 2-point Resistance Test Method / 645 mm² Overlap Contact Area / 1 hour RT Dwell. See note 1. | Gold flex bonded to PCB gold test pad. 6 mm² overlap contact area. 1 hour RT Dwell. See note 1. |
| 9703 |  | 50 | Z | Silver | Low Outgassing Acrylic ECATT | Z- Axis, Low outgassing | < 0.2 | < 0.2 |
| 9704 |  | 50 | Z | Silver | Low Outgassing Acrylic ECATT | Z-axis, High adhesion, Low outgassing | < 0.2 | < 0.2 |
| 9705 |  | 50 | Z | Silver | Standard Acrylic ECATT | Z-Axis, Standard outgassing version of 9703 | < 0.2 | < 0.2 |
| 9706 |  | 50 | Z | Silver | High Adhesion Acrylic ECATT | High adhesion version of the 9705 | < 0.2 | < 0.3 |
| 9707 |  | 50 | XYZ | Silver | High Adhesion Acrylic ECATT | High adhesion, "Bond Line Gap/Slit" EMI shielding for High Frequency, Low contact R to SS | < 0.2 | < 0.3 |
| 9709 |  | 50 | XYZ | Silver | Standard Acrylic ECATT | Standard adhesion, "Bond Line Gap/Slit" EMI shielding for High Frequency | < 0.2 | < 0.3 |
| 9709S |  | 50 | XYZ | Silver | Standard Acrylic ECATT | Standard adhesion, "Bond Line Gap/Slit" EMI shielding for High Frequency, Low contact R to SS | < 0.2 | < 0.2 |
| 9709SL |  | 50 | XYZ | Silver | Standard Acrylic ECATT | Premium low liner release version of 9709S | < 0.2 | < 0.2 |
| 7805 |  | 150 | XYZ | Silver | Standard Acrylic ECATT | Thicker ECATT for gap filling | < 1.0 | < 0.2 |
| 7850 |  | 150 | XYZ | Carbon | High Adhesion Acrylic ECATT | Higher thermal conductivity & Thicker ECATT for gap filling | < 1.0 | < 10.0 |
| 7772 |  | 66 | XYZ | Nickle & Alum DC | Medium Adhesion Acrylic D/C | Double coated aluminum foil | < 0.5 | < 2.0 |
| 9712 |  | 125 | XYZ | Carbon | Standard Acrylic ECATT | Non-woven conductive scrim & Standard acrylic adhesive | < 1.5 | < 15.0 |
| 9713 |  | 89 | XYZ | Nickel/C | Standard Acrylic ECATT | Lower R non-woven conductive scrim vs. 9712 & Standard acrylic adhesive | < 0.4 | < 7.5 |
| 9719 |  | 100 | XYZ | Nickel/C | Silicone ECATT | Low surface energy silicone adhesive, Higher temperature resistance, Lower R non-woven conductive scrim vs. 9712 | < 1.0 | < 20.0 |
| 9720S |  | 30 | XYZ | Nickel/Cu | High Adhesion Acrylic ECATT | Lower R non-woven conductive scrim vs. 9713, Thinner scrim design & Medium adhesion | < 0.2 | < 0.5 |
| 9723 |  | 60 | XYZ | Nickel/Cu | High Adhesion Acrylic ECATT | Lower R non-woven conductive scrim vs. 9713, Thinner scrim design & High adhesion | < 0.2 | < 0.4 |
| 9750 |  | 50 | XYZ | Nickel/Cu | High Adhesion Acrylic ECATT | Lower R non-woven conductive scrim vs. 9713 & High adhesion | < 0.2 | < 0.5 |
| 9732 |  | 100 | XYZ | Nickel/Cu | Medium Adhesion Acrylic ECATT | Lower R non-woven conductive scrim vs. 9713, Thicker scrim design & High adhesion | < 0.2 | < 2.5 |
| 9760 |  | 50 | XYZ | Nickel/Cu | High / Low Adhesion Double sided reworkable Acrylic ECATT | Easier rework as greater Face Side to Back Side adhesion delta. Easier rework version of 9725. High and Low adhesion sides. | < 0.2 | < 0.8 |
| 9764 |  | 150 | XYZ | Nickel/Cu | High / Low Adhesion Double sided reworkable Acrylic ECATT | Easier rework as greater Face Side to Back Side adhesion delta. Easier rework and thicker version of 9732. High and Low adhesion sides. | < 0.5 | < 5.0 |
| 9780 |  | 200 | XYZ | Nickel/Cu | High / Low Adhesion Double sided reworkable Acrylic ECATT | Easier rework as greater Face Side to Back Side adhesion delta. Easier rework and thicker version of 9732. High and Low adhesion sides. | < 0.5 | < 5.0 |

ECATT Basic Comparative Reference Table: Based on the suggested "ECATT Selection Process", the end user should identify 2-4 ECATT products to test in an application to determine fitness for use. As each application is unique, it is difficult to identify the "Optimum" ECATT product without testing the ECATT products in an end use assembly design. The ECATT Selection Process of "Good-Better-Best" ranks products as they might perform in a nominal application. As each ECATT may employ different conductive particles, scrim or non-woven, thickness variations, acrylic adhesive type, etc., they will perform differently based on end use application – hence the need for the end users' own comparative testing. The following technical information and data should be considered representative or typical and should not be used for specification purposes.

Note 1: Test & performance results will vary based on items such as, but are not limited to: Contact area; Assembly method; Testing conditions; Normal variations in product performance from one mfg. lot to a different mfg. lot of material – along with the normal variations found in a material within a mfg. lot (i.e., thickness, available conductive material in an actual sample tested, variations in conductive filler materials and uniformity of conductive materials dispersed within a lot of material, variations in adhesives, etc.); Test methods; Environmental aging; Exact test surface material type utilized, etc. The "Copper to Copper" & "Gold Flex to PCB" testing also should be noted for the differences related to the "Contact area" difference in the Test Methods (645 mm² vs. 6 mm²) as this does impact the test results. Testing of ECATT materials and the noted test substrates does not imply that the ECATT is suitable for an end use application of similar materials. End user is responsible to determine if an ECATT and substrate combination is fit for use in their intended end use application.

Note 2: More ECATT options are available. Chart references typical type options. Contact your 3M Technical Service Representative for more details.

Hard Coating Layer
ITO Layer
LCD Glass
Driver LC
AL39UL

3M™ EMI Custom Foil Tape AL39UL/3006ALB

3M™ EMI Absorbers AB5100/AB6005/AB7050
to reduce EMI noise level on flex/connector.

3M EMI Absorbers AB5100/AB6005/AB7050
to reduce EMI noise within device.

3M™ Flux Field Directional Material AB5016RF/RFIC15
for improved NFC & RFID performance.

3M Flux Field Directional Material RFIC/EM16TF/EM80KM
for improved Wireless Power Efficiency.

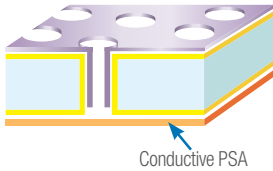
Is Grounding Bias degrading your antenna or data flex signal to noise (S/N) performance?

| Problem | Solution |
|---|---|
| Electrical Bias Degrades Performance Poor Antenna or Data Flex Signal/Noise ratio | Effectively Ground Device Optimized Signal/Noise Ratio |
| Internal Device Bias +2.0 V Antenna -Grounding not effective Signal Data Flex +0.0 V Ground | No Device Bias +0.0 V Antenna Assembly optimized for grounding using 3M ECATT Signal Data Flex +0.0 V Ground |
| If device is not well grounded, the "bias" voltage in the device acts as a "transmitter" of a signal that the signal line flex, antenna flex, etc. pick up, leading to poor S/N performance and higher error rates. | Device is well grounded so the "bias" voltage in the device is "baseline" and no "RF signal" is emitted. Optimized Antenna and data flex S/N performance. 3M ECATT 9707, 9709S, 9720S and 9750 |

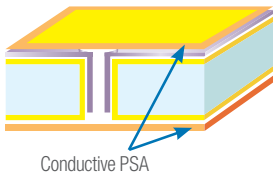
3M EMI/EMC Solutions

Electrically Conductive Cushioning Gasket Selections

3M™ Electrically Conductive Cushioning Gasket
ECG-7033, ECG-7053,
ECG-7073, Single Coat



3M™ Electrically Conductive Cushioning Gasket
ECG-8035, ECG-8055,
ECG-8075, Double Coat



3M™ Electrically Conductive Gaskets solutions encompass three distinct product types:

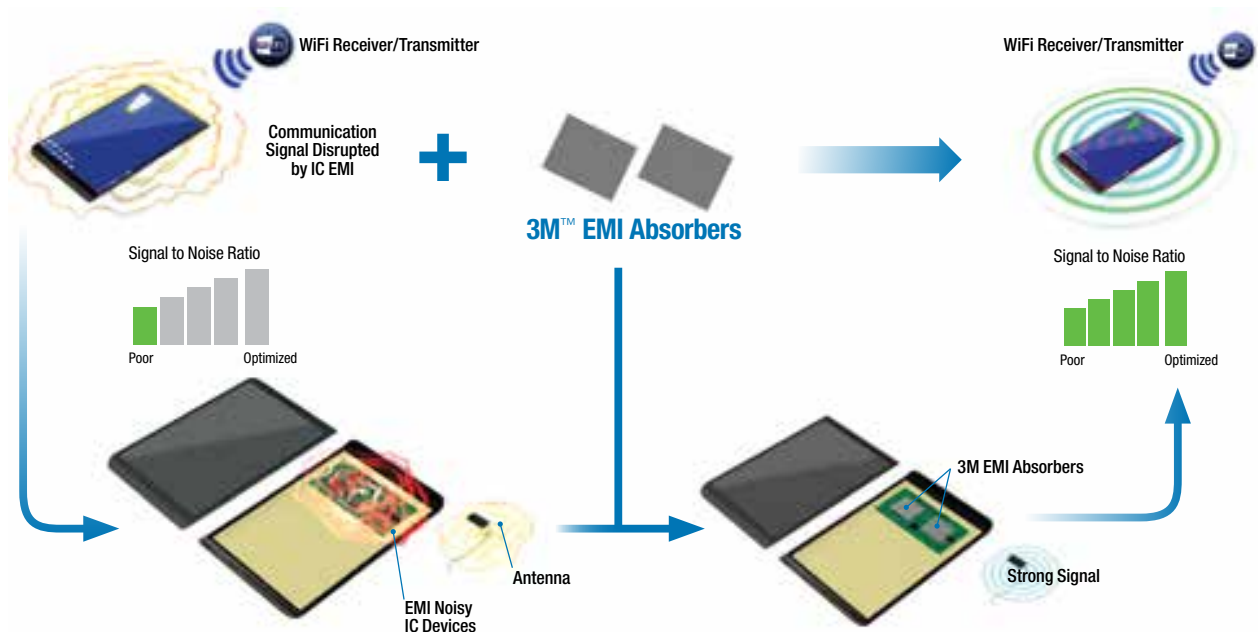
- 3M Electrically Conductive Gaskets (**ECG**): Single coated and double coated conductive foam products (less than 1mm thickness)
- 3M Metal Shielding Gaskets (**MSG**): Very soft single coated conductive foam products with a metal carrier (greater than 1 mm thickness).
- 3M Electrically Conductive Acrylic Pads (**eCAP**): Solid core single coated acrylic conductive gaskets with a conductive fabric carrier (less than 1 mm thickness).

The 3M ECG series has two versions. The single coated version ECG-70xx and the double coated version ECG-80xx. The 3M MSG products are available in greater than 1mm thickness with a metal carrier layer that is either a metal foil or a magnetic foil type. The eCAP product 7830N is an acrylic conductive ECATT with a conductive fabric carrier layer to make a single sided eCAP gasket product.

| Product | Conductive Carrier Type | Conductive Adhesive / Fillers | Conductive Core | Total Thickness (mm) | Features |
|-------------------------|-------------------------|---|---|--|---|
| eCAP 7830N | Conductive Fabric | Acrylic adhesive with Ni coated graphite filler / 1 side, single coated | Acrylic adhesive with Ni coated graphite filler | 0.2, 0.3, 0.4, 0.5 | XYZ electrical conductivity, single sided, provides EMI Shielding and Grounding, Good adhesion to many substrates. |
| ECG-70xx (ex: ECG-7033) | Conductive Fabric | Acrylic adhesive with Ni filler / 1 side, single coated | Metal plated open cell urethane foam | 0.33, 0.53, 0.73 (0.xx) | XYZ electrical conductivity, Conformable-Soft, single sided, provides EMI Shielding and Grounding, Good adhesion to many substrates, single sided adhesive. |
| ECG-80xx (ex: ECG-8035) | Conductive Fabric | Acrylic adhesive with Ni filler / 2 sided, double coated | Metal plated open cell urethane foam | 0.35, 0.55, 0.75 (0.xx) | XYZ electrical conductivity, Conformable-Soft, provides EMI Shielding and Grounding, Good adhesion to many substrates, dual sided adhesive. |
| MSG-6xxx (MSG-6180) | Metal Foil | Acrylic adhesive with Ni filler / 1 side, single coated | Metal plated open cell foam | 0.6, 1.0, 1.8 (optional thicknesses/ inquire @ 3M) | XYZ electrical conductivity, Very Conformable-Soft, single sided, provides EMI Shielding and Grounding, Good adhesion to many substrates, single sided adhesive |

3M EMI Absorbers & 3M Grounding Solutions for Optimized Antenna Performance

3M EMI Absorbers and 3M ECATT Grounding Solutions (Conductive PSA ECATT, Conductive Foils & Fabrics) provide for an optimized antenna performance solution. Absorbers reduce line of sight or reflected EMI noise near an antenna, Conductive PSAs and Gaskets offer grounding for a thickness range potential of 0.03 mm to 3.3 mm gaps, to reduce stray flowing currents and associated EMI that degrades antenna performance (S/N).



3M Wide Frequency EMI Absorbers (AB) and 3M Flux Field Directional Materials (FFDM) – Specific Target Application Frequency Range

3M EMI Absorbers (AB) for wide frequency applications:

- 3M EMI Absorbers are used to reduce EMI and RF noise in electronic systems. 3M EMI Absorbers can be applied to noisy traces, ICs and reflective surfaces in an enclosure.

3M Flux Field Directional Materials (FFDM): Wireless Power, NFC, Magnetic Shielding Digitizer, and HAC

- 3M FFDM products are useful for RFID and NFC applications to de-couple the NFC or RFID antenna from metal surfaces by directing the antenna flux fields away from the metal object or surface. 3M FFDM products can also be beneficial in Wireless Power systems to enhance power transfer efficiency between primary sending and receiving antenna coils. FFDMs such as EM80KM also are useful as magnetic field shielding materials in a thin format.

3M Wide Frequency EMI Absorbers (Ab)

| Product | Carrier Binder Polymer and Filler | Adhesive Type | Magnetic Permeability @ 1 MHz | Absorber Thickness ONLY (mm) | Features |
|-------------------|---|---------------------------------------|-------------------------------|---|---|
| AB-5000 Series | Flexible polyethylene resin with magnetic fillers | Acrylic PSA | 30 | 0.1, 0.2, 0.3, 0.5, 1.0 Example: AB-5000 series @ 0.50 mm absorber thickness (without PSA) = AB-5050 | Reduce EMI and RF noise in electronic systems. Apply to noisy traces, ICs and reflective surfaces in an enclosure. |
| AB-5000S Series | Flexible polyethylene resin with magnetic fillers | Acrylic PSA | 55 | 0.1, 0.2, 0.3, 0.5, 1.0 | Improved lower frequency absorber vs. AB-5000 (@ < 1-2 GHz). Reduce EMI and RF noise in electronic systems. Apply to noisy traces, ICs and reflective surfaces in an enclosure. |
| AB-5000HF Series | Flexible poly resin with magnetic fillers | Acrylic PSA | 30 | 0.1, 0.2, 0.3, 0.5, 1.0 | Halogen Free version of the AB-5000 |
| AB-5000SHF Series | Flexible poly resin with magnetic fillers | Acrylic PSA | 55 | 0.1, 0.2, 0.3, 0.5, 1.0 | Halogen Free version of the AB-5000S |
| AB-6000 Series | Flexible poly resin with magnetic fillers laminated to aluminum foil/EMI Shielding & Absorbing combination. | Acrylic PSA or Conductive Acrylic PSA | Varies | See TDS | AB-6000 series combines an EMI Shielding layer with an EMI absorbing layer. Layer configuration can vary. AB-6000 series can be used as an EMI "Shielding Can/ Faraday Cage" design when other options are not practical. Halogen Free version available (AB-6000HF Series). Note: Ultra thin version of design is available as 3M AFM. 3M AFM uses a foil and thin ferrite design @ 0.05 mm – 0.12 mm. |
| AB-7000 Series | Flexible polyethylene resin with magnetic fillers | Acrylic PSA | 110-120 | 0.05, 0.10, 0.20, 0.30, 0.50 Note: ex: AB-7000 series @ 0.30 mm absorber thickness (without PSA) = AB-7030 | Improved lower frequency absorber vs the AB-5000 or AB-5000S (@ < 1 GHz). Reduce EMI and RF noise in electronic systems. Apply to noisy traces, ICs and reflective surfaces in an enclosure. Halogen Free version available (AB-7000HF Series). |

*See technical data sheet (TDS) for added adhesive thickness for each version.

3M Flux Field Directional Materials (FFDM) - Specific Target Application Frequency Range

| Product | Carrier Binder Polymer and Filler | Adhesive Type | Magnetic Permeability @ 13.56 MHz | Features |
|---------------------------|--|---------------|-----------------------------------|---|
| AB-5000R Series (EM45EP) | Flexible polyethylene resin with magnetic fillers | Acrylic PSA | 45 - 50 | AB-5000R series FFDM materials are designed for RFID and NFC applications to de-couple the NFC or RFID antenna from metal surfaces by directing the antenna flux fields away from the metal object or surface. Products can also be evaluated for Wireless Power systems to enhance power transfer efficiency between primary sending and pick-up antenna coils. Products include: AB-5010R @ 0.15 mm/AB-5020R @ 0.2 mm. |
| EM16TF | Sintered ferrite sheet between carrier films with optional PSA | Acrylic PSA | 160 | EM16TF series FFDM materials are designed for RFID and NFC applications to de-couple the NFC or RFID antenna from metal surfaces by directing the antenna flux fields away from the metal object or surface. Products can also be evaluated for Wireless Power systems to enhance power transfer efficiency between primary sending and pick-up antenna coils. Products include: EM16TF @ different overall thicknesses (see TDS). |
| AB-5000RF Series (EM10TF) | Sintered ferrite sheet between carrier films with optional PSA | Acrylic PSA | 105 | AB-5000RF series FFDM materials are designed for RFID and NFC applications to de-couple the NFC or RFID antenna from metal surfaces by directing the antenna flux fields away from the metal object or surface. Products can also be evaluated for Wireless Power systems to enhance power transfer efficiency between primary sending and pick-up antenna coils. Products include: AB-5016RF @ 0.16 mm /AB-5026RF @ 0.26 mm. Thinner options are available. |
| RFIC Series (EM42EP) | Flexible polyethylene resin with magnetic fillers | Acrylic PSA | 42 | RFIC series FFDM materials are designed for RFID and NFC applications to de-couple the NFC or RFID antenna from metal surfaces by directing the antenna flux fields away from the metal object or surface. Products can also be evaluated for Wireless Power systems to enhance power transfer efficiency between primary sending and pick-up antenna coils. Products include: RFIC-XX @ 0.13 mm - 0.33 mm @ multiple thicknesses. See TDS for details. |
| EM13TF | Sintered ferrite sheet between carrier films with optional PSA | Acrylic PSA | 130 | EMxTF series FFDM materials are designed to be evaluated for Wireless Power systems to enhance power transfer efficiency between primary sending and pick-up antenna coils. Optional uses include RFID and NFC applications to de-couple the NFC or RFID antenna from metal surfaces by directing the antenna flux fields away from the metal object or surface. Products include: EM13TF @ different overall thicknesses (see TDS). |
| EM80KM | High permeability magnetic foil with cover film & PSA | Acrylic PSA | 80,000 max | EM80KM series FFDM materials are designed for DC and low frequency magnetic field shielding to be evaluated for Wireless Power systems to enhance power transfer efficiency between primary sending and pick-up antenna coils. Products include: EM80KM @ 0.12 mm (Thinner versions and optional multi-layer designs are available for optimized thickness and flux field interaction). |

Note: Reference EM # Letter-Letter (i.e., EM80KM)
- EM = Electro-Magnetic
- # = Permeability Peak
- 1st Letter: K=x1000, H=x100, T=x10, E=x1
- 2nd Letter = EM Material Type: M = Magnetic foil, F = Ferrite, P = Polymer composite with magnetic fillers.

After EM##LL, the product is identified by overall thickness in mm (ttt) and one- or two-sided adhesive (A).

Example: EM45EP @ 0.15 mm thickness with PSA on one side = EM45EP-ttt-A = EM45EP-015-1

Note that Ferrite Type always has a film on the non-PSA side.

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 Issued: 5/14 9699HB
 60-5002-0453-6

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